

Material Composition Specification

DPAK-2L Case



Device average mass **376.7 mg**
 Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	silicon carbide	0.37%	1.40	SiC	409-21-2	0.350%	1.32	3,504
				Al	7429-90-5	0.017%	0.065	173
				Ti	7440-32-6	0.001%	0.005	13
				Ni	7440-02-0	0.001%	0.005	13
				Au	7440-57-5	0.001%	0.005	13
bond wire	aluminum	0.13%	0.50	Al	7429-90-5	0.133%	0.50	1,327
leadframe	Cu alloy	65.06%	245.01	Cu	7440-50-8	65.012%	244.90	650,119
				Sn	7440-31-5	0.029%	0.11	292
leadframe plating	tin	0.021%	0.08	Sn	7440-31-5	0.021%	0.08	212
die attach	high temperature solder paste	0.62%	2.34	Pb	7439-92-1	0.592%	2.23	5,920
				Sn	7440-31-5	0.016%	0.06	159
				Ag	7440-22-4	0.013%	0.05	133
encapsulation*	EMC GREEN	33.27%	125.34	silica (fused)	60676-86-0	25.522%	96.14	255,216
				epoxy resin	29690-82-2	3.326%	12.53	33,263
				phenol resin	9003-35-4	1.664%	6.27	16,645
				carbon black	1333-86-4	0.101%	0.38	1,009
				aluminum hydroxide	21645-51-2	2.660%	10.02	26,599
termination plating	matte tin	0.539%	2.03	Sn	7440-31-5	0.539%	2.03	5,389

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.